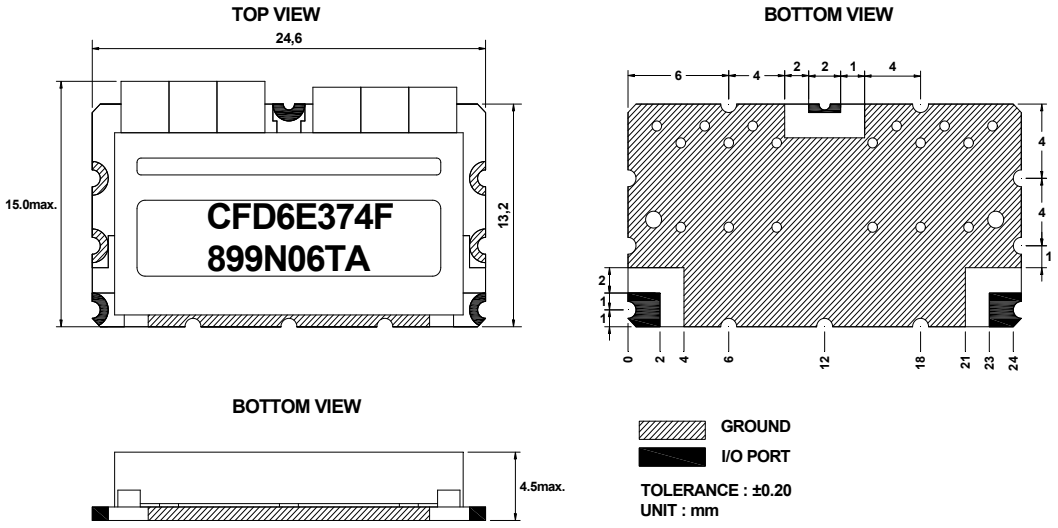
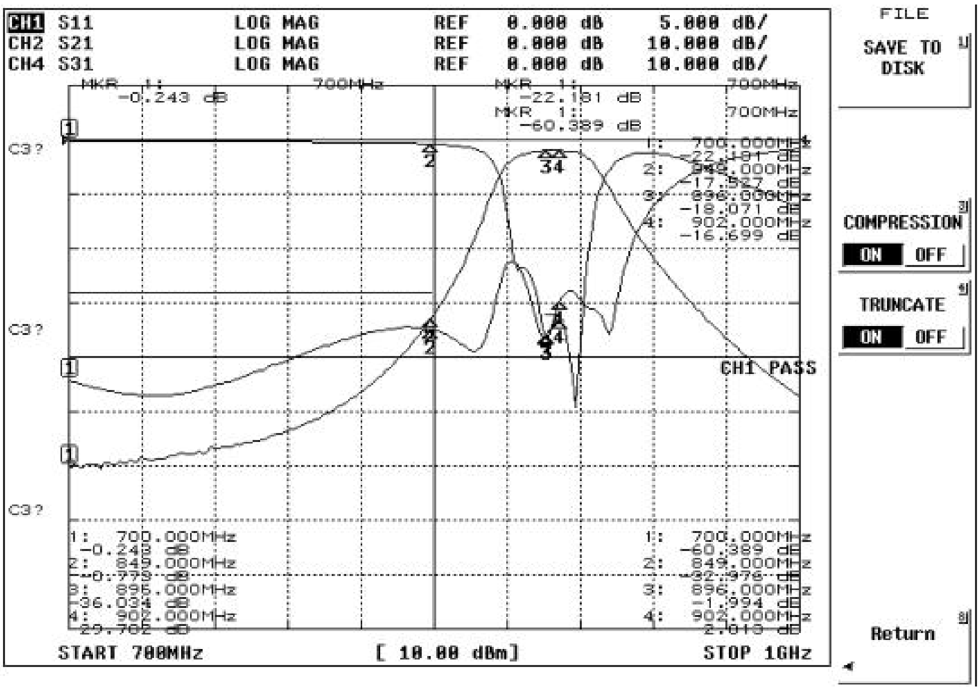
Electrical Specification

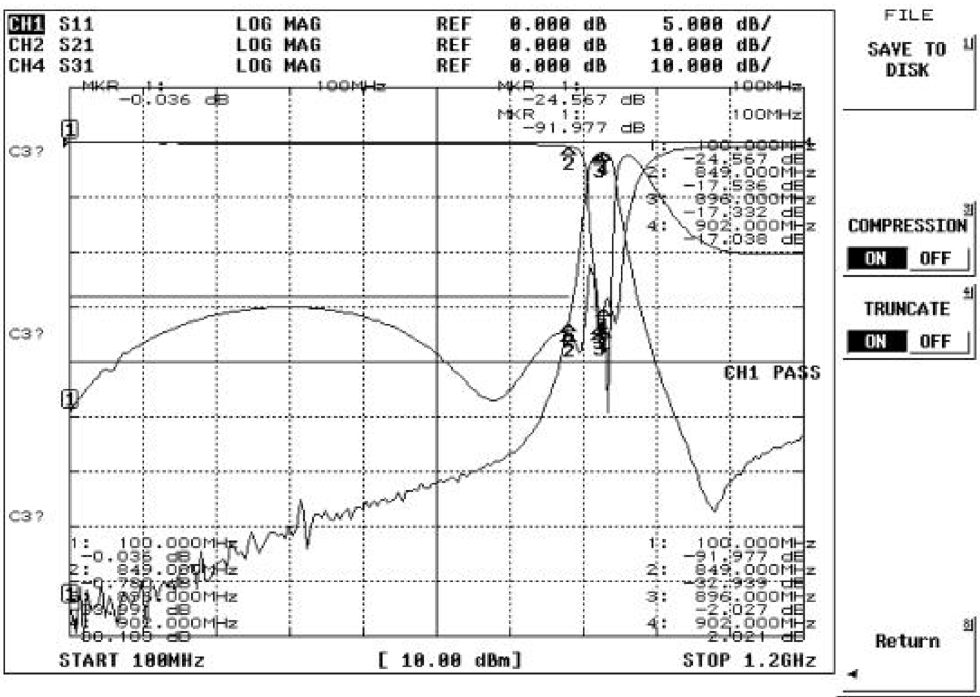
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	374.5	899.0	MHz
Bandwidth [BW]	fo ± [100.0~849.0]	fo ±3.0 [896.0~902.0]	MHz
Insertion Loss in BW	1.0	2.5	dB max
Ripple in BW	0.8	0.5	dB max
Return Loss in BW	14.0	16.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	20 dB min. @ [896~902]	20 dB min. @[100 ~ 849]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
Group Delay Variation			ns max
Input Power	1.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40℃ to +85℃		

Mechanical Specification

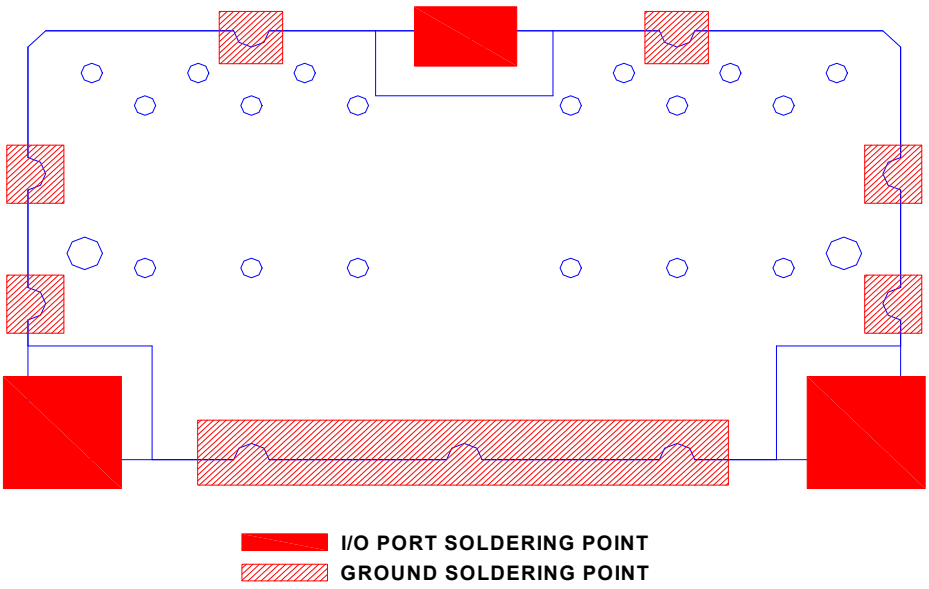


Plot Data

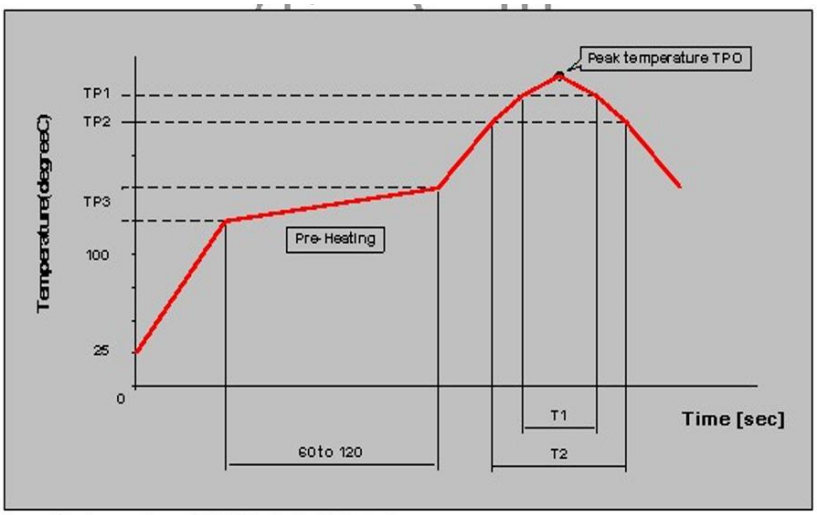

CH1 S11 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S31 LOG MAG REF 0.000 dB 10.000 dB/
CH1 PASS
START 700MHz
[10.00 dBm]
STOP 1GHz
FILE
SAVE TO DISK
COMPRESSION
ON OFF
TRUNCATE
ON OFF
Return


CH1 S11 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S31 LOG MAG REF 0.000 dB 10.000 dB/
CH1 PASS
START 100MHz
[10.00 dBm]
STOP 1.2GHz
FILE
SAVE TO DISK
COMPRESSION
ON OFF
TRUNCATE
ON OFF
Return

Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	___	___	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180